

Prelaminated contactless inlays for card manufacturing

@RFID offers advanced RFID solutions for card manufacturing worldwide. The **Prelaminated contactless inlays** are flexible solution suitable for any production or application, usable for direct printing or over-lamination.

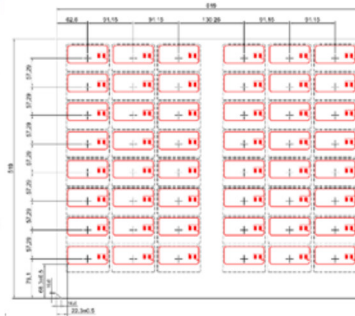
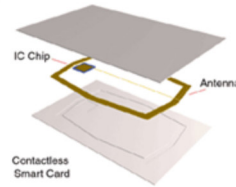
The complex multilayer structure that incorporates the contactless coil can be based on PVC, PET or PC substrates with various final thicknesses (from 0.15 to 0.55mm).

The integrated contactless technology is based on a copper (CU) wired antenna following different layouts or tuning frequencies.

The IC Chip can be pre-integrated or specific connection pads can offer the possibility of a later embedding of a contactless/contact module.

Various layouts or configurations are available following customers' preferences of layouts, thickness, technology.

Please send us your requirements !



Chips:

HF: ISO/IEC 14443: NXP Mifare Series / NTAG Series

@RFID Compatible Series

HF: ISO/IEC 15693: NXP I-Code Series

Dual Frequency Configuration: LF/HF/UHF

Dual Interface Configuration: Contact/Contactless

Technical:

Physical Features:

Material: PVC/PET/PC

Working temperature: -30°C ÷ 70°C

Durability: 3-5 years

Layout: Up to 550x700mm

Multilayer structure: Open or Encapsulated

RFID Features:

Frequency: 125kHz / 13.56MHz / 860-960MHz

Other Features:

Optional Dual Frequency (two antennas + two ICs)

Optional Dual Interface connection pads

Environmental: ROHS compliant

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